

P/1071-1453

METHOD OF BONDING A CONDUCTIVE ADHESIVE AND AN  
ELECTRODE, AND A BONDED STRUCTURE OBTAINED THEREBY

ABSTRACT OF THE DISCLOSURE

5           The present invention relates to a method of bonding  
a conductive adhesive and an electrode together, which is  
capable of obtaining electrical bonding between a  
conductive electrode and an electrode. In this method, a  
conductive adhesive containing a conductive filler and an  
10       organic binder is coated on an electrode having a layer  
formed thereon by plating a low-melting-point material,  
and then heated to cure the organic binder and melt the  
plated layer on the electrode. As a result, the  
conductive filler contained in the adhesive enters the  
15       plated layer to obtain strong bonding between the plated  
layer and the conductive filler.